

NEW HVM tool for next generation package substrates



High yields

Particle control

Best-in-class surface distribution

Touch-free PTH equipment for $L/S < 5/5 \mu\text{m}$

High yield manufacturing is essential for the production of ultra fine-line IC substrates. G-Plate® is the next generation solution to overcome all major challenges that limit yield rates. A key feature is the patented equalized curtain flow system to achieve a homogeneous high solution flow along the panel surface. In conjunction with MKS' Atotech's dedicated Printoganth® GP series, the system enables ultra thin electroless copper deposits with best-in-class surface distribution and an excellent throwing power into blind micro vias and their wedges.

Features and benefits

- High yield manufacturing of ultra fine-lines of $5/5 \mu\text{m}$ and below
- Touch-free transportation
 - Single panel processing
- Particle control
 - 100% filtration of the solution delivered to panel
 - Clean room conditions for panel chamber
 - Vacuum dryer instead of blower system
- Equalized curtain flow
 - Best-in-class surface distribution
 - Superior solution exchange into BMVs
 - Excellent throwing power
 - Minimized nano void occurrence
- HVM tool, 120 panels/h
 - Automated process control
 - Industry leading control software VCS by MKS